

# High-speed double diode Rev. 3 — 29 June 2010

Product data sheet

#### **Product profile** 1.

#### 1.1 General description

Two high-speed switching diodes fabricated in planar technology, and encapsulated in a small SOT143B Surface-Mounted Device (SMD) plastic package. The diodes are not connected.

#### 1.2 Features and benefits

■ High switching speed:  $t_{rr} \le 6$  ns

Reverse voltage: V<sub>R</sub> ≤ 60 V

Repetitive peak reverse voltage: V<sub>RRM</sub> ≤ 60 V Repetitive peak forward current: I<sub>FRM</sub> ≤ 600 mA

AEC-Q101 qualified

Small SMD plastic package

#### 1.3 Applications

High-speed switching in e.g. surface-mounted circuits

#### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>F</sub>	forward current		[1][2]	-	200	mA
I <sub>R</sub>	reverse current	V <sub>R</sub> = 60 V	-	-	100	nA
V <sub>R</sub>	reverse voltage		-	-	60	V
t <sub>rr</sub>	reverse recovery time		<u>[3]</u> _	-	6	ns

<sup>[1]</sup> Single diode loaded.

- [2] Device mounted on an FR4 Printed-Circuit Board (PCB).
- [3] When switched from  $I_F$  = 400 mA to  $I_R$  = 400 mA;  $R_L$  = 100  $\Omega$ ; measured at  $I_R$  = 40 mA.



**High-speed double diode** 

## 2. Pinning information

Table 2. Pinning

Table 2.	Pinning		
Pin	Description	Simplified outline	Graphic symbol
1	cathode (diode 1)		
2	cathode (diode 2)	4 3	4 3
3	anode (diode 2)		
4	anode (diode 1)	1 2	
			1 2
			006aab100

## 3. Ordering information

Table 3. Ordering information

Type number	Package			
	Name	Description	Version	
BAS56	-	plastic surface-mounted package; 4 leads	SOT143B	

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
BAS56	*L5

[1] \* = -: made in Hong Kong

\* = p: made in Hong Kong

\* = t: made in Malaysia

\* = W: made in China

#### **High-speed double diode**

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RRM</sub> repetitive peak reverse voltage	•		-	60	V
	voltage		[1] -	120	V
$V_R$	reverse voltage		-	60	V
			[1] -	120	V
l <sub>F</sub>	forward current		[2][3]	200	mA
			[2][4]	150	mA
I <sub>FRM</sub>	repetitive peak forward		[3] _	600	mA
current	current		[4] _	430	mA
I <sub>FSM</sub>	non-repetitive peak forward	square wave	<u>[5]</u>		
	current	t <sub>p</sub> = 1 μs	-	9	Α
		t <sub>p</sub> = 100 μs	-	3	Α
		t <sub>p</sub> = 10 ms	-	1.7	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2] _	250	mW
Tj	junction temperature		-	150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

<sup>[1]</sup> Series connection.

## 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W
R <sub>th(j-t)</sub>	thermal resistance from junction to tie-point		-	-	360	K/W

<sup>[1]</sup> Device mounted on an FR4 PCB.

<sup>[2]</sup> Device mounted on an FR4 PCB.

<sup>[3]</sup> Single diode loaded.

<sup>[4]</sup> Double diode loaded.

<sup>[5]</sup>  $T_j = 25$  °C prior to surge.

#### **High-speed double diode**

## 7. Characteristics

Table 7. Characteristics

 $T_i = 25$  °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{F}$	forward voltage	I <sub>F</sub> = 200 mA	<u>[1]</u> -	-	1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 60 V	-	-	100	nΑ
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 150 °C	-	-	100	μΑ
		V <sub>R</sub> = 120 V	[2] _	-	100	nΑ
		V <sub>R</sub> = 120 V; T <sub>j</sub> = 150 °C	[2] _	-	100	μΑ
$C_d$	diode capacitance	$f = 1 MHz; V_R = 0 V$	-	-	2.5	pF
t <sub>rr</sub>	reverse recovery time		[3] _	-	6	ns
$V_{FR}$	forward recovery voltage		<u>[4]</u> _	-	2	V
			[5]	-	1.5	V

<sup>[1]</sup>  $T_{amb} = 25$  °C; device has reached the thermal equilibrium when mounted on an FR4 PCB.

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<sup>[2]</sup> Series connection.

<sup>[3]</sup> When switched from  $I_F$  = 400 mA to  $I_R$  = 400 mA;  $R_L$  = 100  $\Omega$ ; measured at  $I_R$  = 40 mA.

<sup>[4]</sup> When switched from  $I_F = 400 \text{ mA}$ ;  $t_r = 30 \text{ ns}$ .

<sup>[5]</sup> When switched from  $I_F = 400 \text{ mA}$ ;  $t_r = 100 \text{ ns}$ .

#### **High-speed double diode**

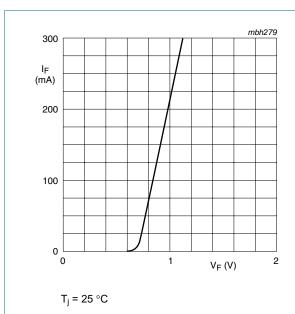
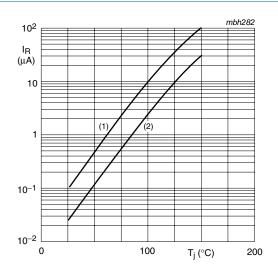


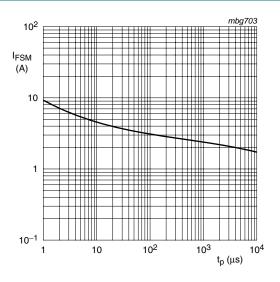
Fig 1. Forward current as a function of forward voltage; typical values



(1)  $V_R = 60 \text{ V}$ ; maximum values

(2)  $V_R = 60 \text{ V}$ ; typical values

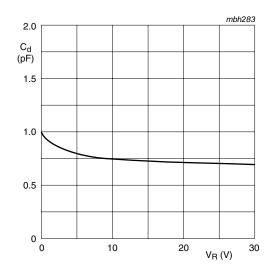
Fig 3. Reverse current as a function of junction temperature



Based on square wave currents.

T<sub>i</sub> = 25 °C; prior to surge

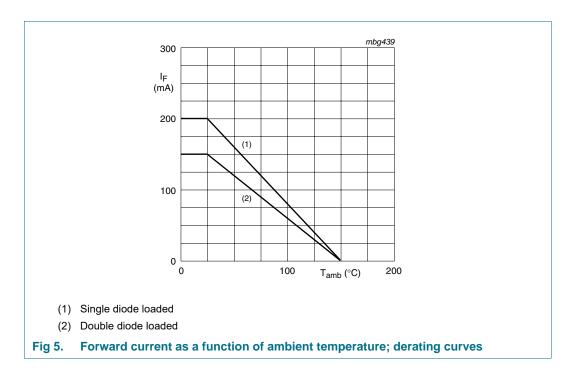
Fig 2. Non-repetitive peak forward current as a function of pulse duration



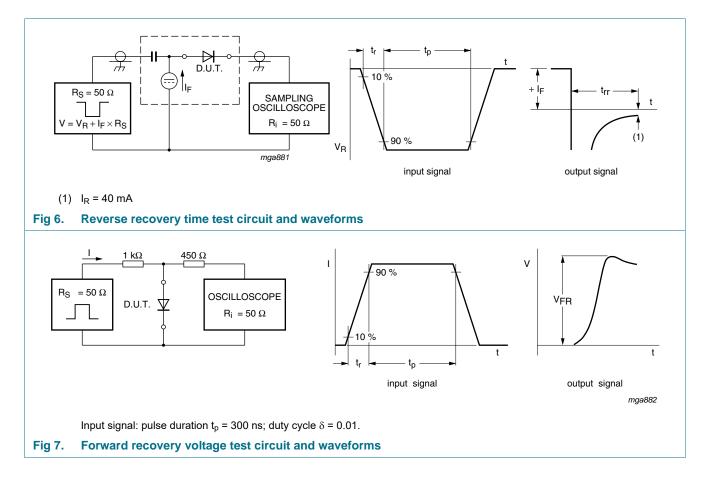
 $f = 1 \text{ MHz}; T_j = 25 ^{\circ}\text{C}$ 

Fig 4. Diode capacitance as a function of reverse voltage; typical values

#### **High-speed double diode**



## 8. Test information



BAS56

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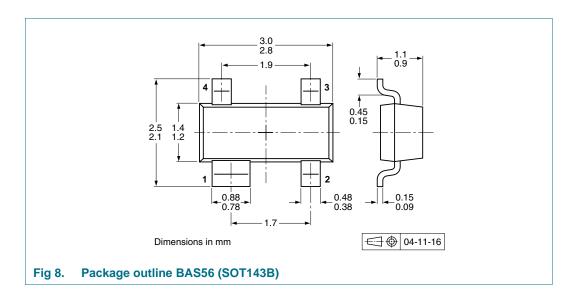
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**High-speed double diode** 

## 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline

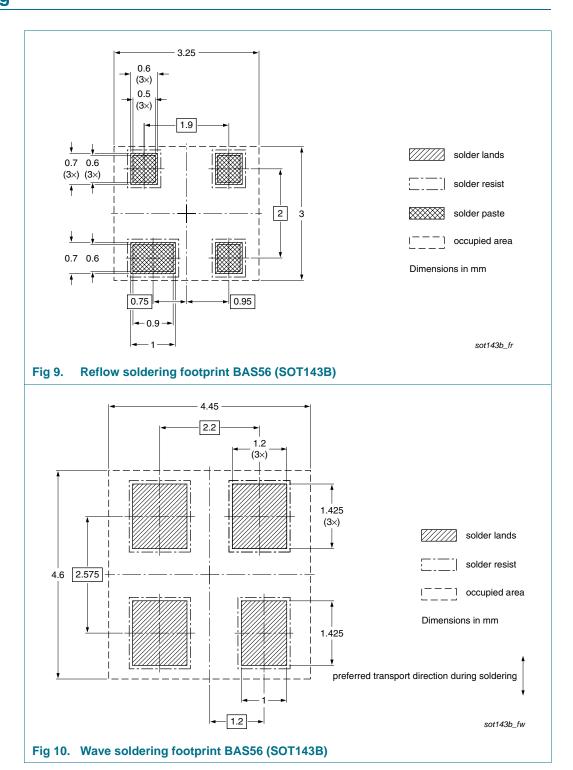


## 10. Packing information

Please refer to packing information on www.nexperia.com.

#### **High-speed double diode**

## 11. Soldering



**Product data sheet** 

High-speed double diode

## 12. Revision history

## Table 9. Revision history

Release date	Data sheet status	Change notice	Supersedes		
20100629	Product data sheet	-	BAS56_2		
		redesigned to comply w	ith the new identity		
<ul> <li>Legal texts h</li> </ul>	nave been adapted to the ne	ew company name whe	re appropriate.		
<ul> <li>Section 1.1 "</li> </ul>	'General description": amen	nded			
<ul> <li>Section 4 "M</li> </ul>	larking": updated				
Table 1 "Quick reference data": added					
Section 8 "Test information": added					
Figure 8: superseded by minimized package outline drawing					
Section 10 "Packing information": added					
• <u>Section 11 "S</u>	Soldering": added				
Section 13 "I	Legal information": updated				
19960910	Product specification	-	BAS56_1		
19960423	Product specification	-	-		
	The format of guidelines of guidelines of the section 1.1       Section 4 "M       Table 1 "Quidelines of the section 8 "To the section 8 "To the section 10 "In the section 10 "In the section 10 "In the section 11 "Section 13 "In the section 14 "In the se	<ul> <li>20100629 Product data sheet</li> <li>The format of this data sheet has been guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new Section 1.1 "General description": amer</li> <li>Section 4 "Marking": updated</li> <li>Table 1 "Quick reference data": added</li> <li>Section 8 "Test information": added</li> <li>Figure 8: superseded by minimized pact</li> <li>Section 10 "Packing information": added</li> <li>Section 11 "Soldering": added</li> <li>Section 13 "Legal information": updated</li> <li>19960910 Product specification</li> </ul>	<ul> <li>The format of this data sheet has been redesigned to comply we guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name whether section 1.1 "General description": amended</li> <li>Section 4 "Marking": updated</li> <li>Table 1 "Quick reference data": added</li> <li>Section 8 "Test information": added</li> <li>Figure 8: superseded by minimized package outline drawing</li> <li>Section 10 "Packing information": added</li> <li>Section 11 "Soldering": added</li> <li>Section 13 "Legal information": updated</li> <li>19960910 Product specification -</li> </ul>		

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## 13. Legal information

#### 13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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## High-speed double diode

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

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## High-speed double diode

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